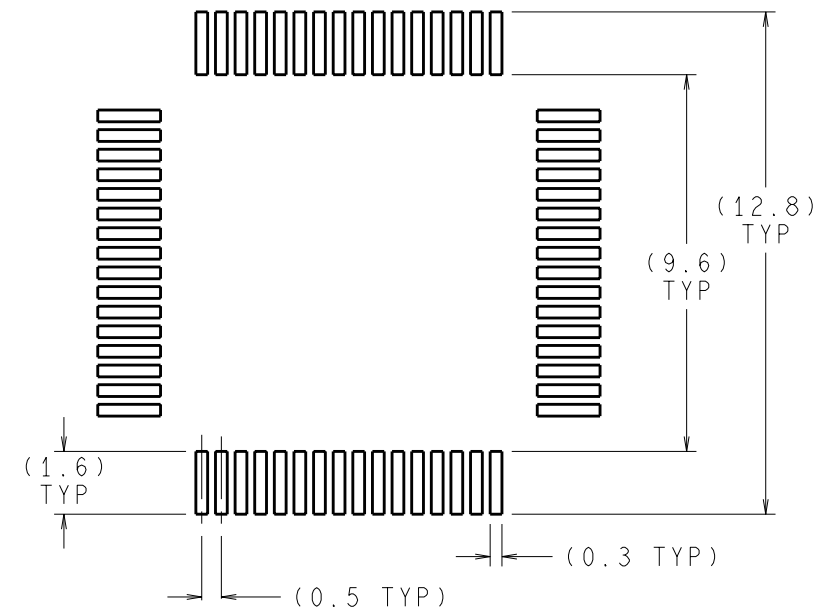
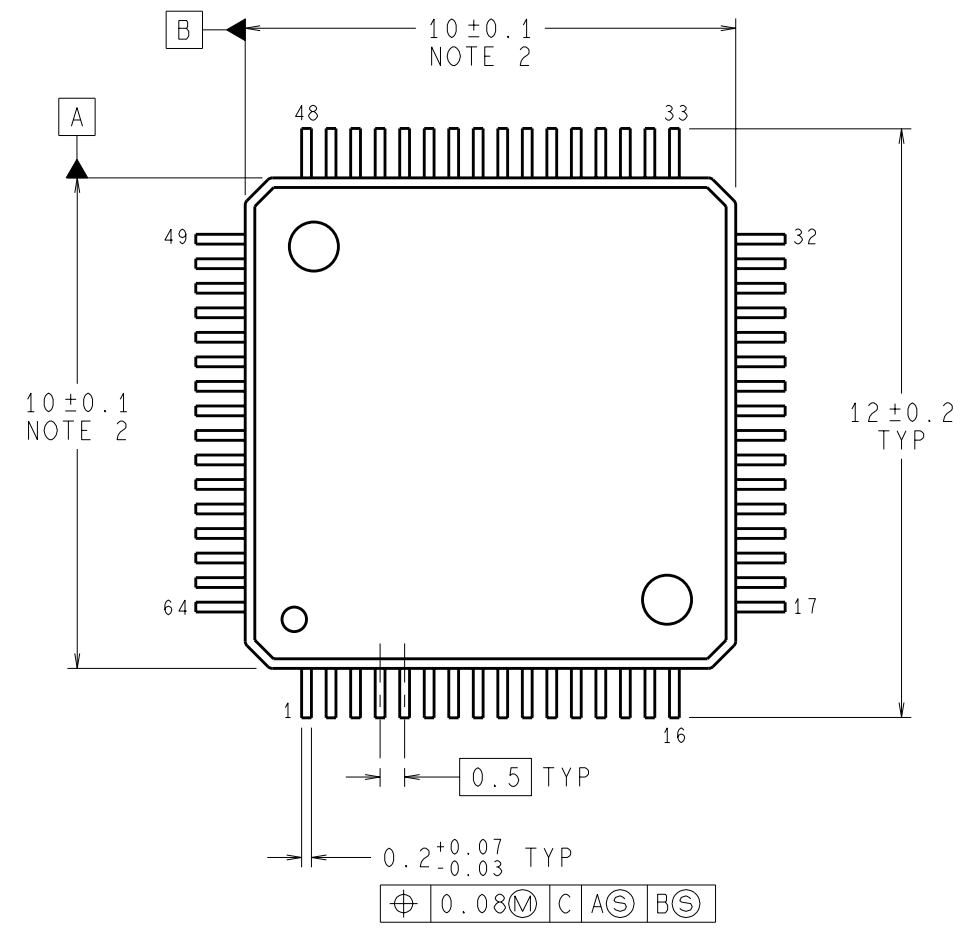
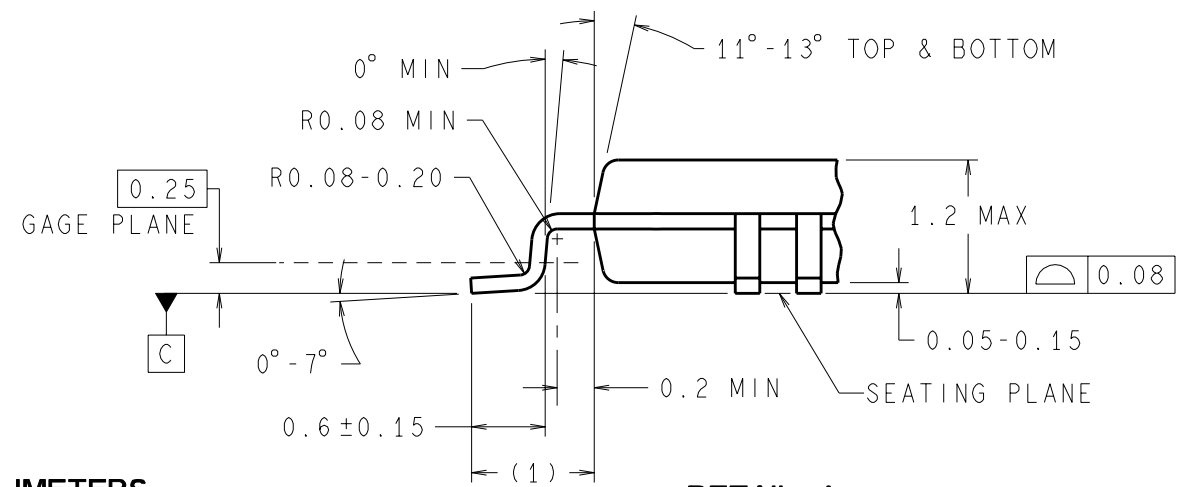
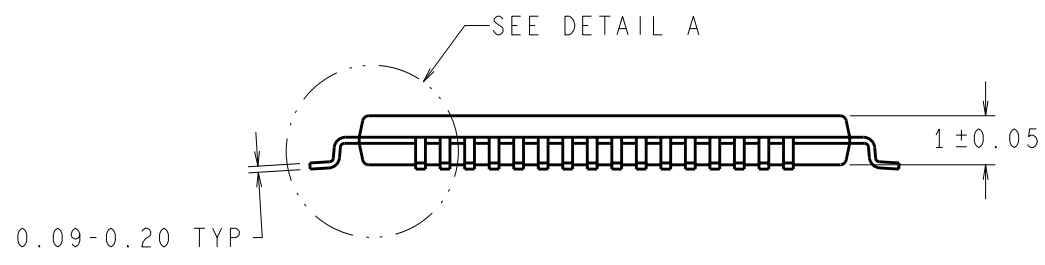


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12379	05/01/2000	MS/RW



LAND PATTERN RECOMMENDATION



DETAIL A
TYP, SCALE: 25X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION ACD,
DATED FEB 1999.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DRAWN MARTA SUCHY	05/01/2000				
DFTG. CHK. THANH LEQUANG	05/01/2000				
ENGR. CHK. RANDALL WALBERG	05/01/2000	TQFP, JEDEC METRIC, 10 X 10 X 1.0mm, 64 LEAD			
 PROJECTION INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-VEC64A	REV A
DO NOT SCALE DRAWING				SHEET 1 of 1	